



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C32M32MD2A-25BIN									
Part Weight:		181.69mg									
NO.	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM	
1	Molding Compound	G760LB	105.398	Epoxy Resin	Resin	Trade Secret	8.00%	8.432	4.6408%	46,408	
				Phenol Resin A	Resin	Trade Secret	3.00%	3.162	1.7403%	17,403	
				Phenol Resin B	Resin	Trade Secret	3.00%	3.162	1.7403%	17,403	
				Silica(Amorphous) A	Base material	60676-86-0	75.00%	79.049	43.5073%	435,073	
				Silica(Amorphous) B	Base material	7631-86-9	2.50%	2.635	1.4502%	14,502	
				Metal Hydroxide	Base material	Trade Secret	8.00%	8.432	4.6408%	46,408	
				Carbon Black	Additive	1333-86-4	0.50%	0.527	0.2900%	2,900	
2	Substrate	BT	52.418				100.00%	52.418	28.8502%	288,502	
3	DAF	EM760	1.345	Acrylic resin	Base material	Trade Secret	50.00%	0.673	0.3701%	3,701	
				Silica, amorphous	Base material	7631-86-9	45.00%	0.605	0.3331%	3,331	
				Phenol resin	Base material	Trade Secret	5.00%	0.067	0.0370%	370	
4	Wire	Au 0.8mil	1.381	GOLD	Base material	7440-57-5	99.9992%	1.381	0.7601%	7,601	
				Beryllium	Base material	7440-41-7	0.0008%	0.000	0.0000%	0	
5	Solder Ball	M705	12.954	Tin (Sn)	Plating material	7440-31-5	96.50%	12.501	6.8802%	68,802	
				Ag	Plating material	7440-22-4	3.00%	0.389	0.2139%	2,139	
				Cu	Plating material	7440-50-8	0.50%	0.065	0.0356%	356	
6	Die		8.194	Si	Chip	7440-21-3	100.00%	8.194	4.5099%	45,099	
			181.69mg					100.0000%	1000000		

Alliance Memory Inc. 511 Taylor Way, San Carlos, CA 94070 TEL: (650) 610-6800 FAX: (650) 620-9211
 Alliance Memory Inc. reserves the right to change products or specification without notice.